



## Final Product Change Notification

201602003F01

**Issue Date:** 22-May-2016

**Effective Date:** 03-Sep-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



# QUALITY

### Change Category

<input checked="" type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

Release of 8 inch wafer diameter for low VCEsat (BISS) transistors

### Details of this Change

Release of production using 8 inch wafer diameter for products in SOT23 and SOT89 (SC-62) package.

In addition to the announced changes in the APCN, there will be a change of the top metal thickness for all types affected by this FPCN. The thickness of the top metallization will be adapted from 2.1µm to 2.2µm resp. from 1.4µm to 1.5µm. Please refer to the Self Qualification Report for details.

Old products: Production using 6 inch wafer diameter, top side metallization thickness 2.1µm or 1.4µm

Changed products: Production using 6 and 8 inch wafer diameter, top side metallization thickness 2.2µm or 1.5µm (for the 8 inch wafer)

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

#### Why do we implement this Change

To increase flexibility and volume ramp-up.

#### Identification of Affected Products

The 8 inch products can be identified by a marker on the die surface.

### Product Availability

#### Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 13-June-2016.

#### Production

Planned first shipment 29-Aug-2016

#### Impact

No impact to the products' functionality anticipated.

#### Data Sheet Revision

No impact to existing datasheet

#### Disposition of Old Products

Supply using 6 inch wafer will be continued.

#### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 21-Jun-2016.

#### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support

**e-mail address** DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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